

74LV138

3-to-8 line decoder/demultiplexer; inverting

Rev. 4 — 4 March 2016

Product data sheet

1. General description

The 74LV138 is a low-voltage Si-gate CMOS device that is pin and function compatible with 74HC138 and 74HCT138.

The 74LV138 is a 3-to-8 line decoder/demultiplexer. It accepts three binary weighted address inputs (A0, A1 and A2) and, when enabled, provides eight mutually exclusive active LOW outputs ($\bar{Y}0$ to $\bar{Y}7$).

There are three enable inputs: two active LOW ($\bar{E}1$ and $\bar{E}2$) and one active HIGH (E3). Every output will be HIGH unless $\bar{E}1$ and $\bar{E}2$ are LOW and E3 is HIGH.

This multiple enable function allows easy parallel expansion of the device to a 1-of-32 (5 lines to 32 lines) decoder with just four 74LV138 devices and one inverter. The 74LV138 can be used as an eight output demultiplexer by using one of the active LOW enable inputs as the data input and the remaining enable inputs as strobes. Unused enable inputs must be permanently tied to their appropriate active HIGH or LOW state.

2. Features and benefits

- Wide operating voltage: 1.0 V to 5.5 V
- Optimized for low voltage applications: 1.0 V to 3.6 V
- Accepts TTL input levels between $V_{CC} = 2.7$ V and $V_{CC} = 3.6$ V
- Typical output ground bounce < 0.8 V at $V_{CC} = 3.3$ V and $T_{amb} = 25$ °C
- Typical HIGH-level output voltage (V_{OH}) undershoot: > 2 V at $V_{CC} = 3.3$ V and $T_{amb} = 25$ °C
- Demultiplexing capability
- Multiple input enable for easy expansion
- Ideal for memory chip select decoding
- Active LOW mutually exclusive outputs
- ESD protection:
 - ◆ HBM JESD22-A114E exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from -40 °C to $+85$ °C and from -40 °C to $+125$ °C



3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74LV138D	-40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74LV138DB	-40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74LV138PW	-40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74LV138BQ	-40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1

4. Functional diagram

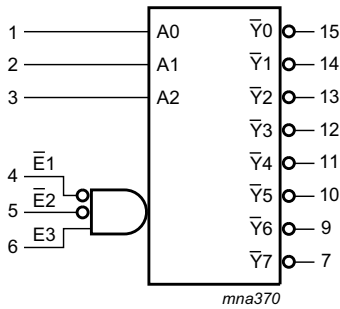


Fig 1. Logic symbol

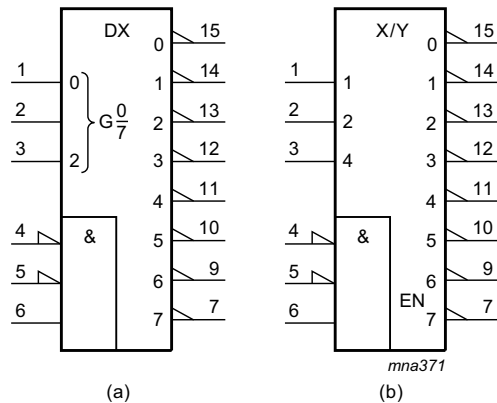


Fig 2. IEC logic symbol

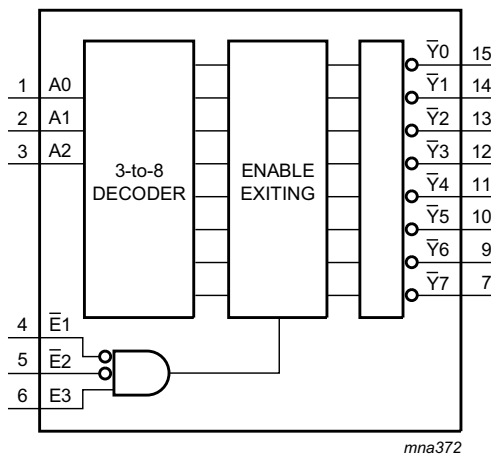


Fig 3. Functional diagram

5. Pinning information

5.1 Pinning

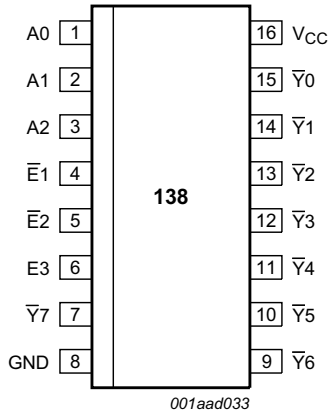
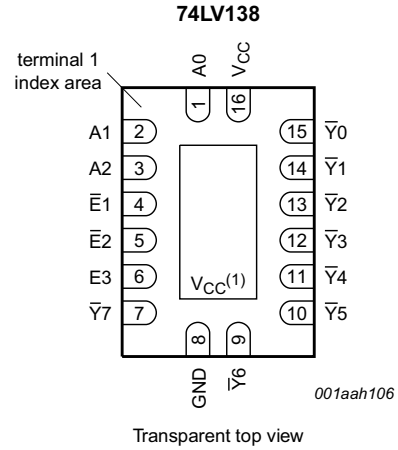


Fig 4. Pin configuration SO16 and (T)SSOP16



- (1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to V_{CC}.

Fig 5. Pin configuration DHVQFN16

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
A0	1	address input
A1	2	address input
A2	3	address input
$\bar{E}1$	4	enable input (active LOW)
$\bar{E}2$	5	enable input (active LOW)
E3	6	enable input (active HIGH)
GND	8	ground (0 V)
$\bar{Y}0$ to $\bar{Y}7$	15, 14, 13, 12, 11, 10, 9, 7	output
V _{CC}	16	supply voltage

6. Functional description

Table 3. Function table

H = HIGH voltage level; L = LOW voltage level; X = don't care

Input						Output							
E1	E2	E3	A0	A1	A2	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
H	X	X	X	X	X	H	H	H	H	H	H	H	H
X	H	X	X	X	X	H	H	H	H	H	H	H	H
X	X	L	X	X	X	H	H	H	H	H	H	H	H
L	L	H	L	L	L	L	H	H	H	H	H	H	H
L	L	H	H	L	L	H	L	H	H	H	H	H	H
L	L	H	L	H	L	H	H	L	H	H	H	H	H
L	L	H	H	H	L	H	H	H	L	H	H	H	H
L	L	H	L	L	H	H	H	H	H	L	H	H	H
L	L	H	H	L	H	H	H	H	H	H	L	H	H
L	L	H	L	H	H	H	H	H	H	H	H	L	H
L	L	H	H	H	H	H	H	H	H	H	H	H	L

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7.0	V
I _{IK}	input clamping current	V _I < -0.5 V or V _I > V _{CC} + 0.5 V [1]	-	±20	mA
I _{OK}	output clamping current	V _O < -0.5 V or V _O > V _{CC} + 0.5 V [1]	-	±50	mA
I _O	output current	V _O = -0.5 V to (V _{CC} + 0.5 V)	-	±25	mA
I _{CC}	supply current		-	50	mA
I _{GND}	ground current		-50	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C			
		SO16 package [2]	-	500	mW
		(T)SSOP16 package [3]	-	500	mW
		DHVQFN16 package [4]	-	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] P_{tot} derates linearly with 8 mW/K above 70 °C.

[3] P_{tot} derates linearly with 5.5 mW/K above 60 °C.

[4] P_{tot} derates linearly with 4.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage ^[1]		1.0	3.3	5.5	V
V_I	input voltage		0	-	V_{CC}	V
V_O	output voltage		0	-	V_{CC}	V
T_{amb}	ambient temperature		-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.0 \text{ V to } 2.0 \text{ V}$	-	-	500	ns/V
		$V_{CC} = 2.0 \text{ V to } 2.7 \text{ V}$	-	-	200	ns/V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	-	-	100	ns/V
		$V_{CC} = 3.6 \text{ V to } 5.5 \text{ V}$	-	-	50	ns/V

[1] The static characteristics are guaranteed from $V_{CC} = 1.2 \text{ V}$ to $V_{CC} = 5.5 \text{ V}$, but LV devices are guaranteed to function down to $V_{CC} = 1.0 \text{ V}$ (with input levels GND or V_{CC}).

9. Static characteristics

Table 6. Static characteristics

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V_{IH}	HIGH-level input voltage	$V_{CC} = 1.2 \text{ V}$	0.9	-	-	0.9	-	V
		$V_{CC} = 2.0 \text{ V}$	1.4	-	-	1.4	-	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2.0	-	-	2.0	-	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$0.7V_{CC}$	-	-	$0.7V_{CC}$	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 1.2 \text{ V}$	-	-	0.3	-	0.3	V
		$V_{CC} = 2.0 \text{ V}$	-	-	0.6	-	0.6	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	-	-	0.8	-	0.8	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	-	$0.3V_{CC}$	-	$0.3V_{CC}$	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$						
		$I_O = -100 \mu\text{A}; V_{CC} = 1.2 \text{ V}$	-	1.2	-	-	-	V
		$I_O = -100 \mu\text{A}; V_{CC} = 2.0 \text{ V}$	1.8	2.0	-	1.8	-	V
		$I_O = -100 \mu\text{A}; V_{CC} = 2.7 \text{ V}$	2.5	2.7	-	2.5	-	V
		$I_O = -100 \mu\text{A}; V_{CC} = 3.0 \text{ V}$	2.8	3.0	-	2.8	-	V
		$I_O = -100 \mu\text{A}; V_{CC} = 4.5 \text{ V}$	4.3	4.5	-	4.3	-	V
		$I_O = -6 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.4	2.82	-	2.2	-	V
$I_O = -12 \text{ mA}; V_{CC} = 4.5 \text{ V}$	3.6	4.2	-	3.5	-	V		

Table 6. Static characteristics ...continued
 Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}						
		I _O = 100 μA; V _{CC} = 1.2 V	-	0	-	-	-	V
		I _O = 100 μA; V _{CC} = 2.0 V	-	0	0.2	-	0.2	V
		I _O = 100 μA; V _{CC} = 2.7 V	-	0	0.2	-	0.2	V
		I _O = 100 μA; V _{CC} = 3.0 V	-	0	0.2	-	0.2	V
		I _O = 100 μA; V _{CC} = 4.5 V	-	0	0.2	-	0.2	V
		I _O = 6 mA; V _{CC} = 3.0 V	-	0.25	0.40	-	0.50	V
		I _O = 12 mA; V _{CC} = 4.5 V	-	0.35	0.55	-	0.65	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 5.5 V	-	-	1.0	-	1.0	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	20.0	-	160	μA
ΔI _{CC}	additional supply current	per input; V _I = V _{CC} - 0.6 V; V _{CC} = 2.7 V to 3.6 V	-	-	500	-	850	μA
C _I	input capacitance		-	3.5	-	-	-	pF

[1] Typical values are measured at T_{amb} = 25 °C.

10. Dynamic characteristics

Table 7. Dynamic characteristics
 GND = 0 V; For test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
t _{pd}	propagation delay	An to \bar{Y}_n ; see Figure 6 ^[2]						
		V _{CC} = 1.2 V	-	75	-	-	-	ns
		V _{CC} = 2.0 V	-	26	44	-	55	ns
		V _{CC} = 2.7 V	-	19	31	-	39	ns
		V _{CC} = 3.0 V to 3.6 V; C _L = 15 pF ^[3]	-	12	-	-	-	ns
		V _{CC} = 3.0 V to 3.6 V ^[3]	-	15	26	-	32	ns
		V _{CC} = 4.5 V to 5.5 V	-	-	17	-	22	ns
		E3, \bar{E}_n to \bar{Y}_n ; see Figure 6 and Figure 7						
		V _{CC} = 1.2 V	-	75	-	-	-	ns
		V _{CC} = 2.0 V	-	26	43	-	53	ns
		V _{CC} = 2.7 V	-	19	30	-	38	ns
		V _{CC} = 3.0 V to 3.6 V; C _L = 15 pF ^[3]	-	14	-	-	-	ns
		V _{CC} = 3.0 V to 3.6 V ^[3]	-	15	25	-	31	ns
		V _{CC} = 4.5 V to 5.5 V	-	-	19	-	24	ns

Table 7. Dynamic characteristics ...continued

$GND = 0\text{ V}$; For test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
C_{PD}	power dissipation capacitance	$C_L = 50\text{ pF}$; $f_i = 1\text{ MHz}$; $V_I = GND\text{ to }V_{CC}$ ^[4]	-	45	-	-	-	pF

- [1] All typical values are measured at $T_{amb} = 25\text{ °C}$.
- [2] t_{pd} is the same as t_{PLH} and t_{PHL} .
- [3] Typical values are measured at nominal supply voltage ($V_{CC} = 3.3\text{ V}$).
- [4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz, f_o = output frequency in MHz
 C_L = output load capacitance in pF
 V_{CC} = supply voltage in V
 N = number of inputs switching
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

11. Waveforms

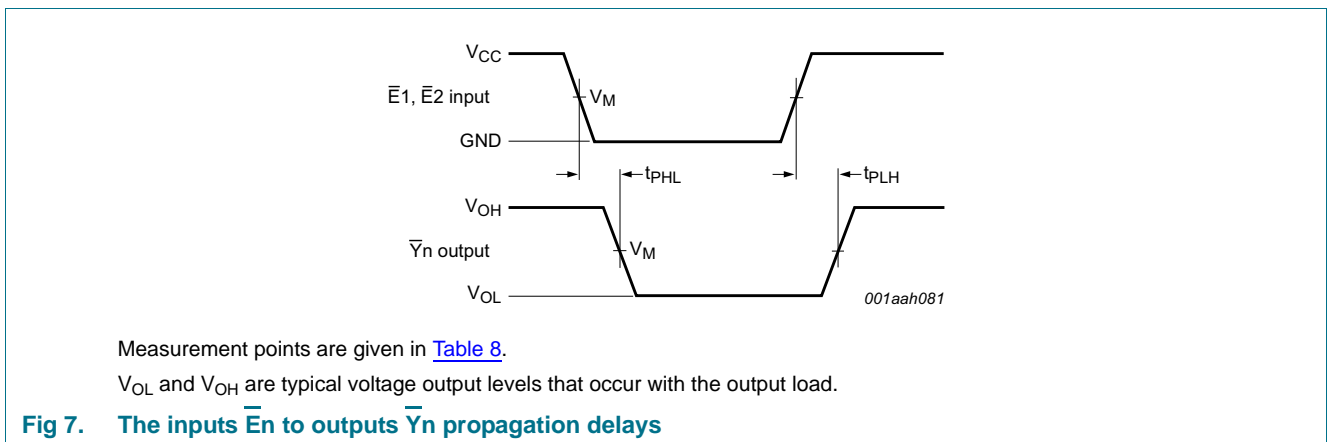
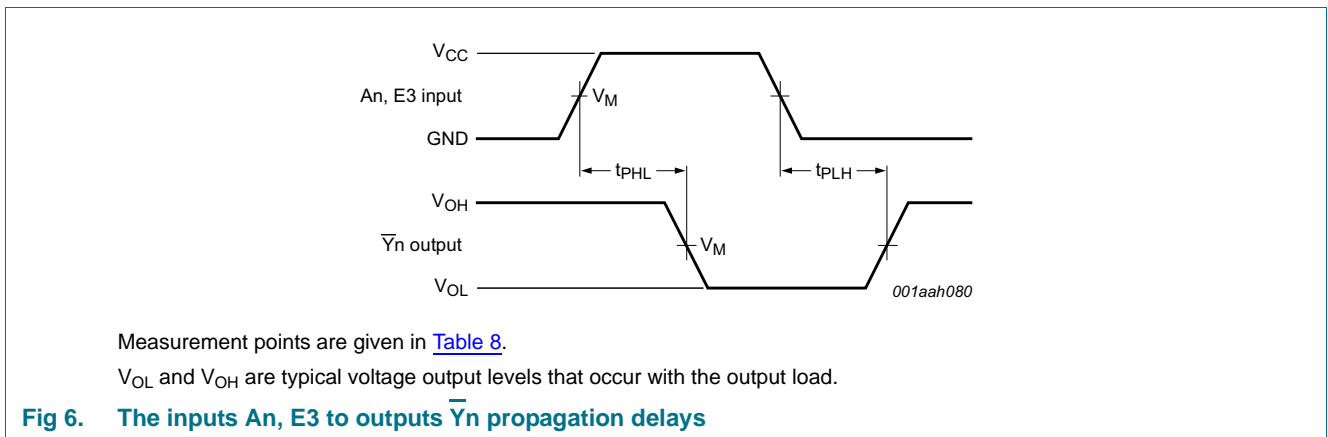
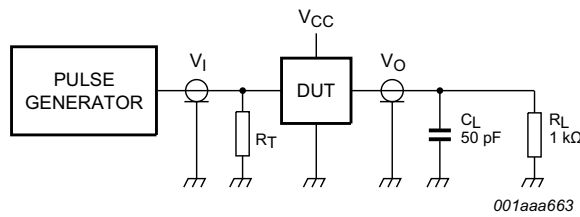


Table 8. Measurement points

Supply voltage	Input	Output
V_{CC}	V_M	V_M
< 2.7 V	$0.5V_{CC}$	$0.5V_{CC}$
2.7 V to 3.6 V	1.5 V	1.5 V
≥ 4.5 V	$0.5V_{CC}$	$0.5V_{CC}$



001aaa663

Test data is given in [Table 9](#).

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

Fig 8. Test circuit for measuring switching times

Table 9. Test data

Supply voltage	Input	t_r, t_f
V_{CC}	V_I	t_r, t_f
< 2.7 V	V_{CC}	≤ 2.5 ns
2.7 V to 3.6 V	2.7 V	≤ 2.5 ns
≥ 4.5 V	V_{CC}	≤ 2.5 ns

12. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

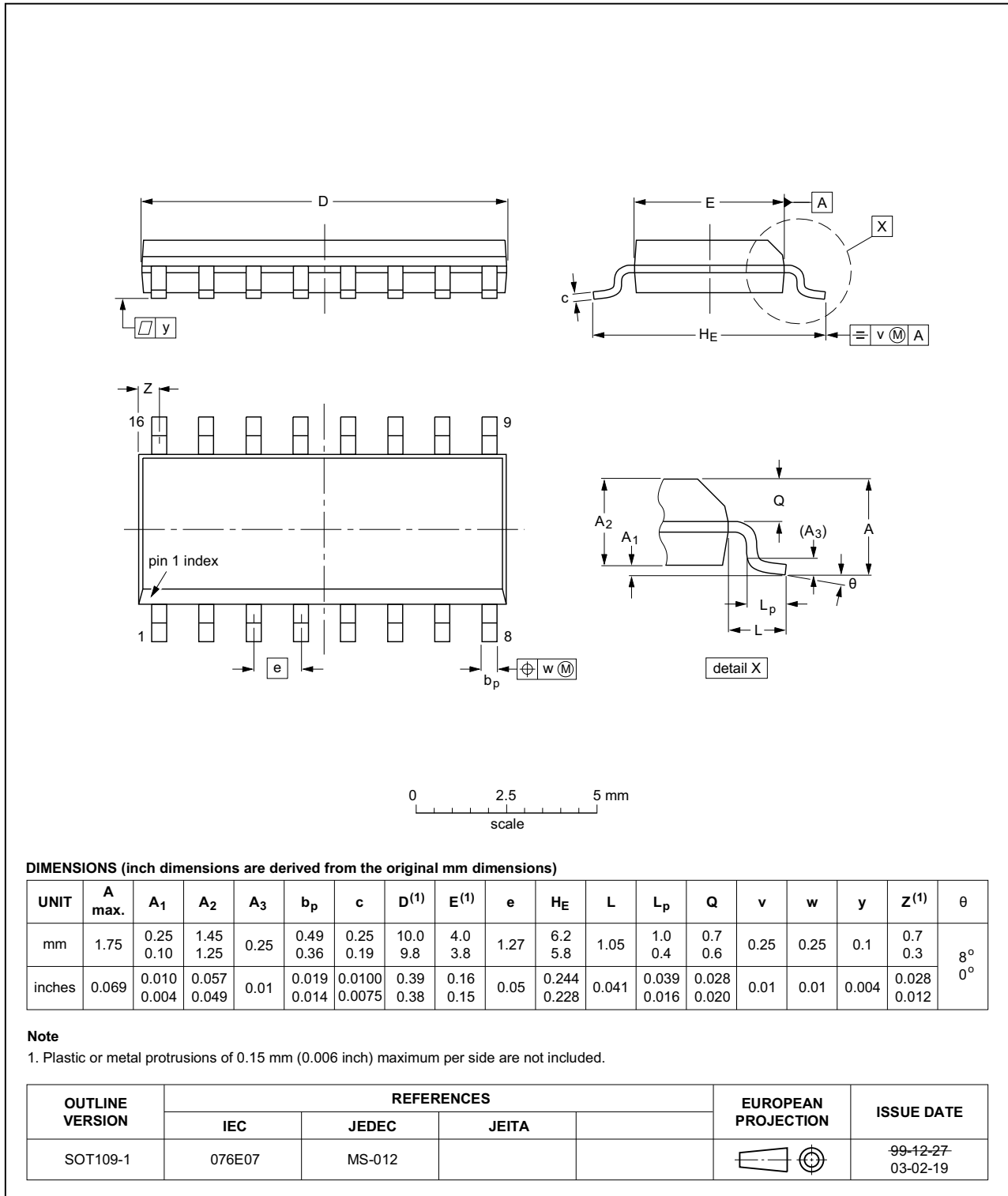


Fig 9. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

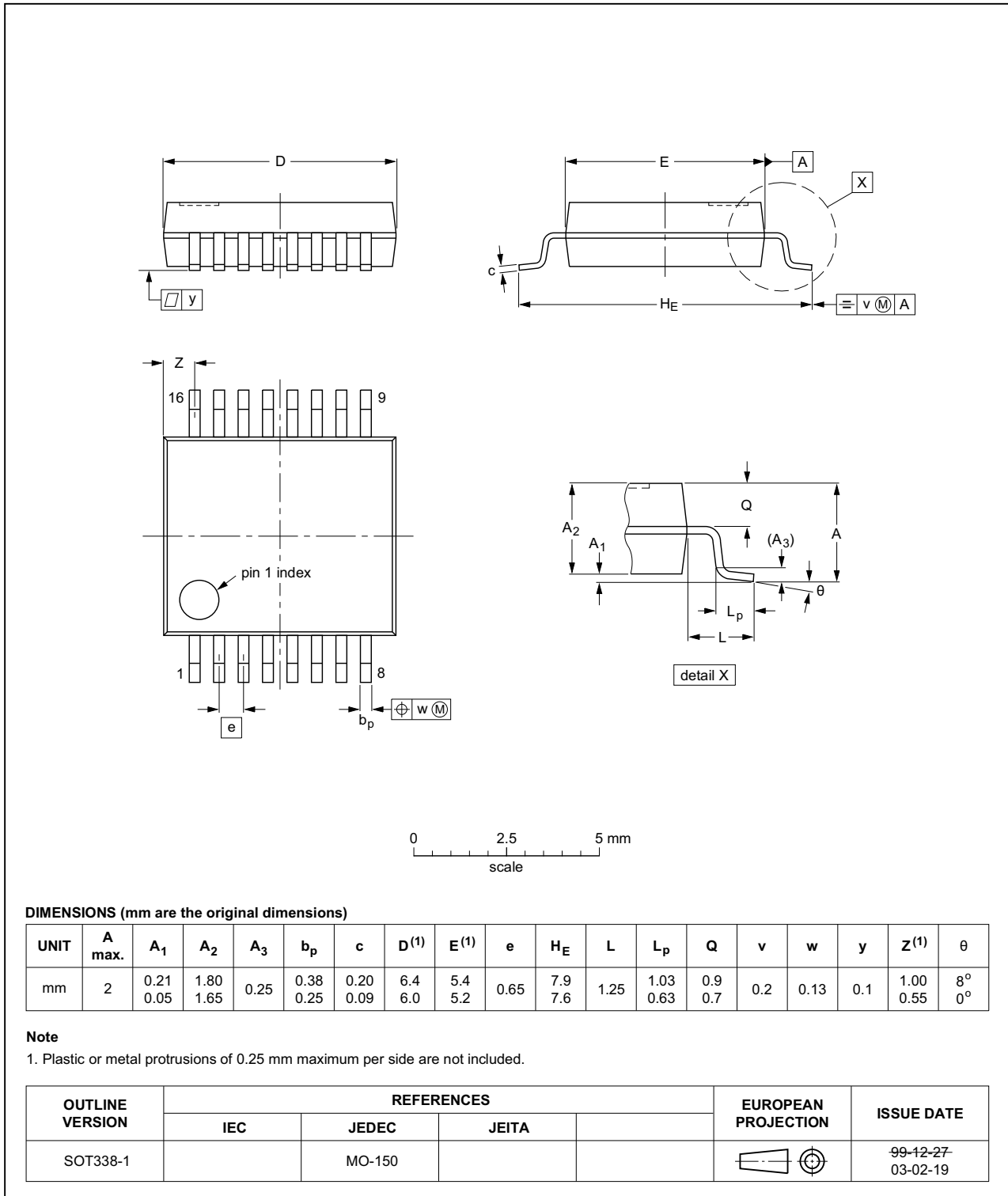


Fig 10. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

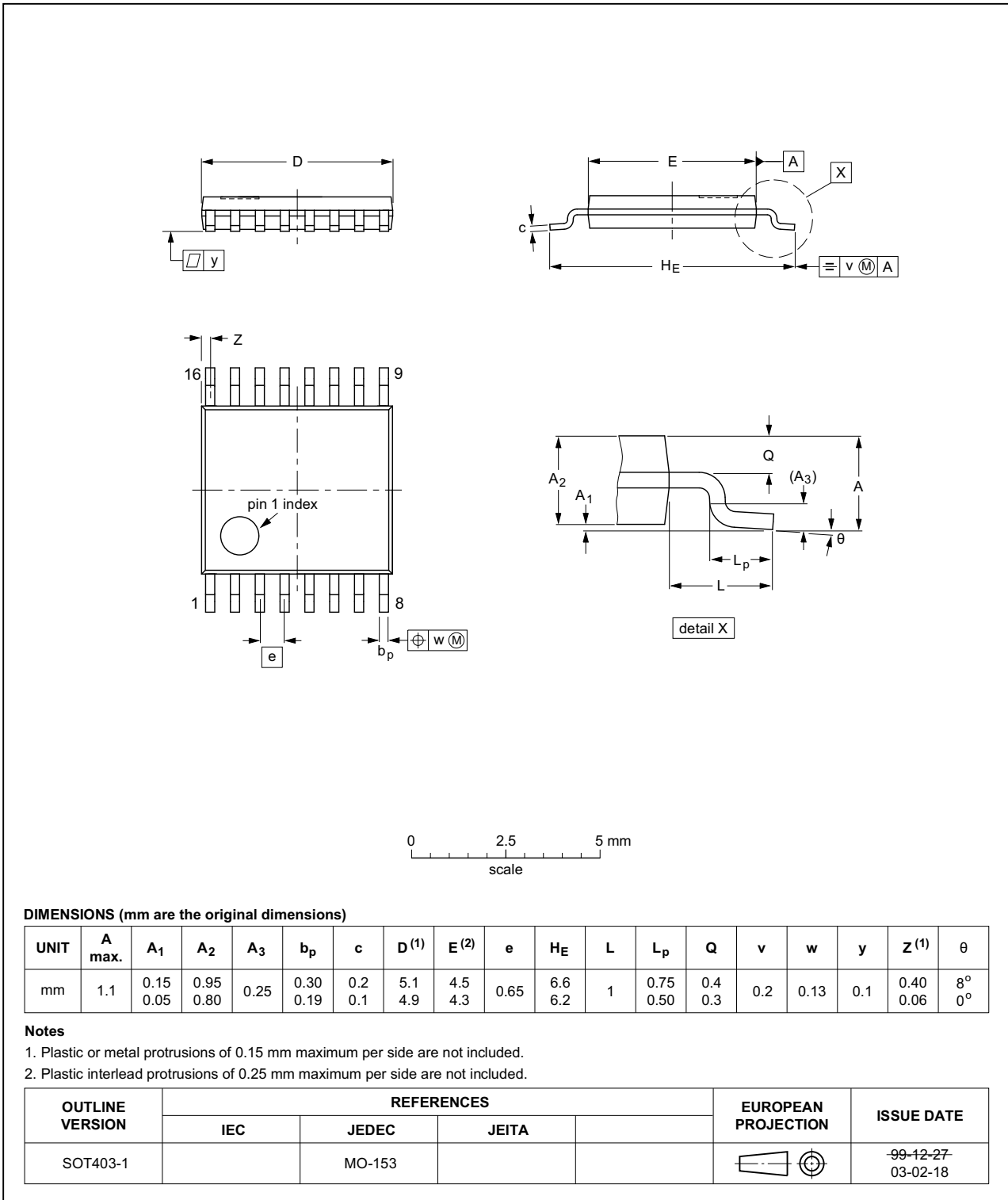


Fig 11. Package outline SOT403-1 (TSSOP16)

DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm

SOT763-1

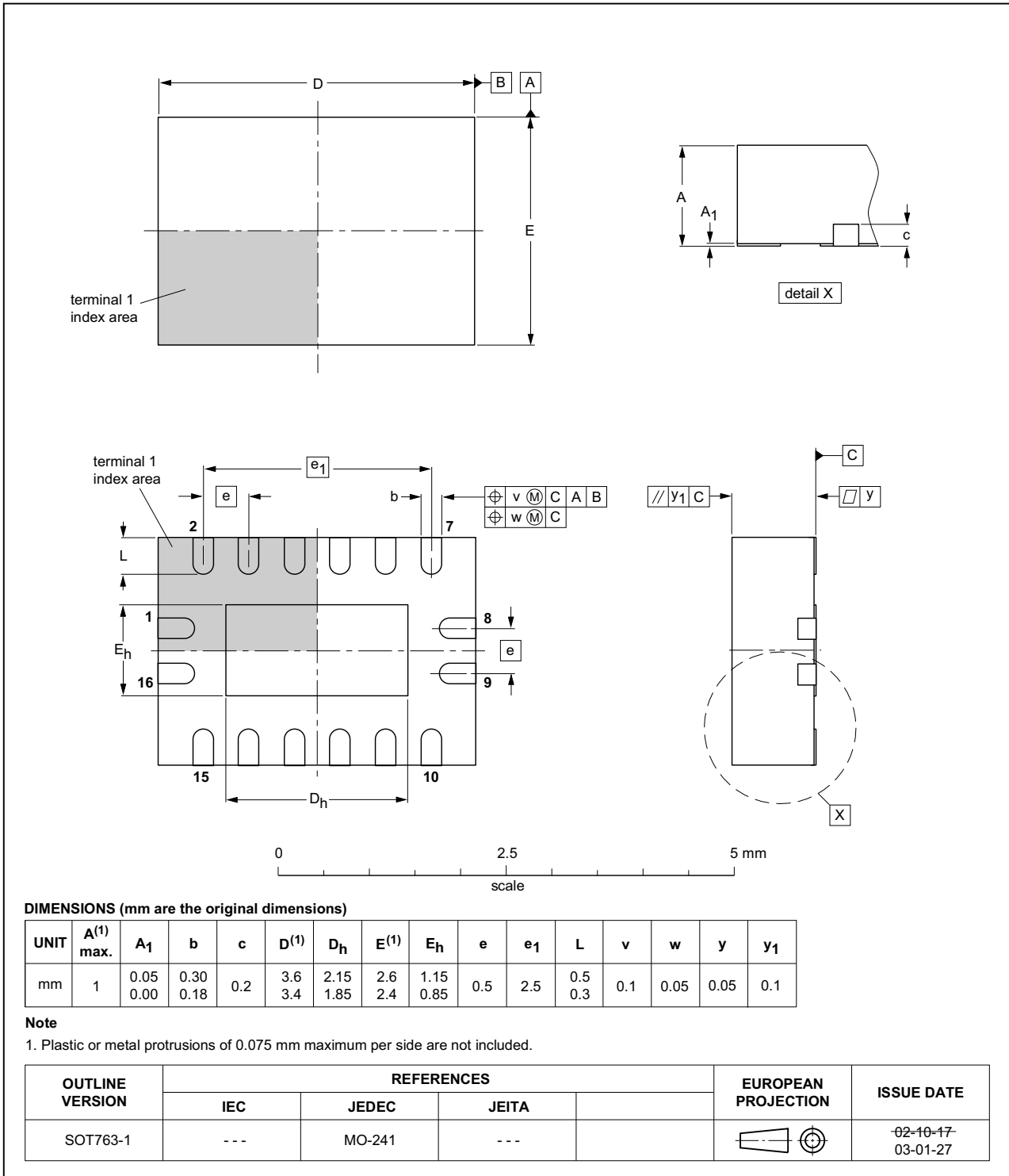


Fig 12. Package outline SOT763-1 (DHVQFN16)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LV138 v.4	20160304	Product data sheet	-	74LV138 v.3
Modifications:	<ul style="list-style-type: none"> Type number 74LV138N (SOT38-4) removed. 			
74LV138 v.3	20071115	Product data sheet	-	74LV138 v.2
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name where appropriate. Section 3: DHVQFN16 package added. Section 8: derating values added for DHVQFN16 package. Section 12: outline drawing added for DHVQFN16 package. 			
74LV138 v.2	19980428	Product specification	-	74LV138 v.1
74LV138 v.1	19970203	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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